

ABSTRACT

A wiring board according to the present invention includes a wiring part formed of one or more layers, a first terminal area disposed on one side of the wiring part in a projecting manner, and a second terminal area disposed on the other side of the wiring part. A resist having an opening for a first terminal area is formed on a surface of a composite made of a plurality of metal layers. A part of a first metal layer of the composite is etched through the opening for a first terminal area to form a hole. The hole is subjected to an electroless plating through the opening of the resist. Thus, the hole is filled with an electroplated layer to form a first terminal area. Then, the resist is removed from the composite, and a wiring layer is formed thereon. Subsequently, a solder resist having an opening for a second terminal area is disposed on the wiring layer. The opening of a second terminal area of the solder resist is subjected to an electroplating so as to form a second terminal area. Removing remaining parts of the composite, a wiring board is completed.